

08-22-2003

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U.S. DEPARTMENT OF COMMERCE U.S. Patent and Trademark Office

(Rev. 03/01) OMB No. 0651-0027 (exp. 5/31/2002) To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof. 1. Name of conveying party(ies): 2. Name and address of receiving party(ies) Name: SUMITOMO MITSUBISHI SILICON NAOKI IKEDA CORPORATION Internal Address: Additional name(s) of conveying party(ies) attached? 🕞 Yes 🌠 No 3. Nature of conveyance: Assignment Merger Street Address: 1-2-1 Shibaura, Minato-ku Security Agreement Cnange of Name City: TOKYO State: JAPAN Zip:105-8634 August 4, 2003 Execution Date:_ 4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is:_____ A. Patent Application No.(s) B. Patent No.(s) 6,277,501 Bl issued August 21, 2001 Additional numbers attached? 📮 Yes 🎇 No 5. Name and address of party to whom correspondence | 6. Total number of a; plications and patents involved: 1 concerning document should be mailed: 7. Total fee (37 CFR 3.41).....\$ 40.00 BREINER & BREINER, L.L.C. ☐ Enclosed Internal Address: Authorized to be charged to deposit account 8. Deposit account number: Street Address:____ North Henry Street 02-3690 P.O. Box 19290 (Attach duplicate copy of this page if paying by deposit account) City: Alexandria State: VA Zip:22320-0290 DO NOT USE THIS SPACE 9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true a.:d correct and any attached copy is a true copy of the original document. Mary J. Breiner Name of Person Signing Total number of pages including cover sheet, attachments, and documents:

(4708/Fujikawa/Oshida) Mail documents to be recorded with required cover sheet information to: ommissioner of Patents & Trademarks, Box Assignments

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PATENT

REEL: 014402 FRAME: 0223

ASSIGNMENT

WHEREAS, I, NAOKI IKEDA, a citizen of Japan residing at 806, 3-5-44, Kaisei, Saga-shi, Saga-ken, Japan 849-0934, am a co-inventor with Takashi Fujikawa as to the invention as described and claimed in U.S. Patent No. 6,277,501 B1 issued August 21, 2001 for "SILICON EPITAXIAL WAFER AND METHOD FOR MANUFACTURING THE SAME" (hereafter "The Patent");

AND WHEREAS, SUMITOMO MITSUBISHI SILICON CORPORATION, a corporation of Japan and having a place of business at 1-2-1 Shibaura, Minato-ku, Tokyo 105-8634, Japan, is desirous of acquiring the entire right, title, and interest in and to said invention and in and to The Patent;

NOW, THEREFORE, for good and valuable consideration, I do hereby sell, assign, transfer, and set over unto the said SUMITOMO MITSUBISHI SILICON CORPORATION, its legal representatives, successors, and assigns, the entire right, title, and interest in and to all inventions whether joint or sole disclosed and claimed in The Patent and in and to any and all divisional, continuation or reissue applications that may be filed for United States Letters Patent for any of said inventions and in and to all patents of the United States which may be issued for said invention; and

UPON SAID CONSIDERATION, I do hereby agree with the said assignee that I will not execute any writing or do any act whatsoever conflicting with these presents, and that I will, at any time upon request, without further or additional consideration, but at the expense of the said assignee, execute such additional assignments and other writings and do such additional acts as said assignee may deem necessary or desirable to perfect the assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining divisional, continuation or reissued Letters Patent of the United States on said invention, and in enforcing any rights or choses in action accruing as a result of The Patent or such applications or patents, by giving testimony in any proceedings or transactions involving The Patent or such applications or patents, and by executing preliminary statements and other affidavits, it being understood that the foregoing covenant and agreement shall bind, and inure to the benefit of, the assigns and legal representatives of assignor and assignee.

Date luguet 4, 200)

NAOKI IKEDA

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